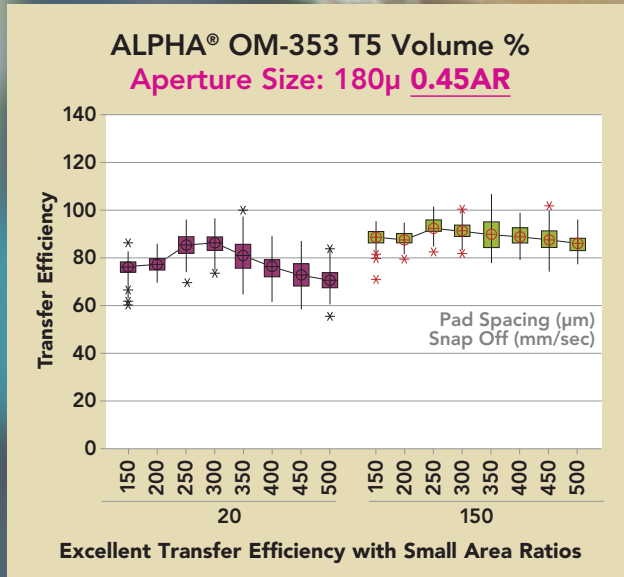


ALPHA® OM-353 LEAD-FREE, ZERO HALOGEN,* ULTRA FINE-FEATURE SOLDER PASTE



Alpha Innovation Leading the Way!

- ALPHA® OM-353 is a low silver paste capable of reflowing type 5 powder in an air environment.
- Designed to meet market segments requiring ultra-fine feature applications.
- Tested to give excellent printing performance and **high print volume repeatability** down to 180µm pad size dimension with a 60° angled squeegee on stencil at 50 mm/s speed, 2 mm/s release speed and 0.18 N/m pressure printing parameters.

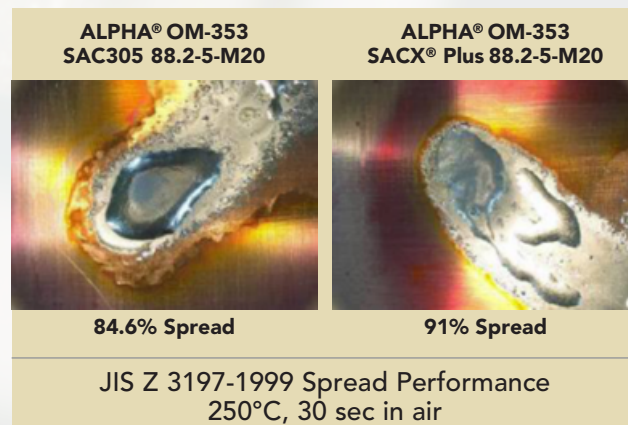
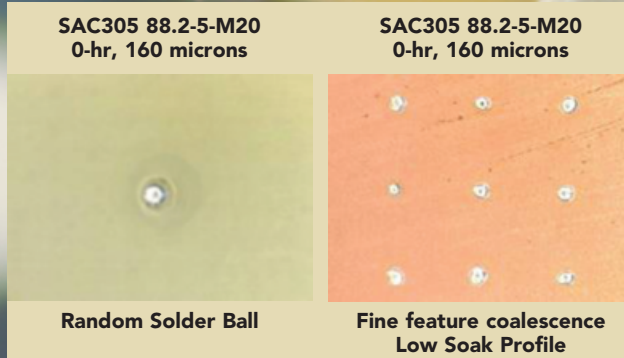
Excellent Fine Feature Coalescence

- ALPHA® OM-353 has been shown to yield good coalescence under the following harsh conditions:

POWDER SIZE	PROFILE (AIR)	ALLOY	
		SAC305	SACX 0307
T5	Low Soak	160 microns	170 microns
	High Soak	160 microns	170 microns

ALPHA® OM-353 Offers Many Benefits

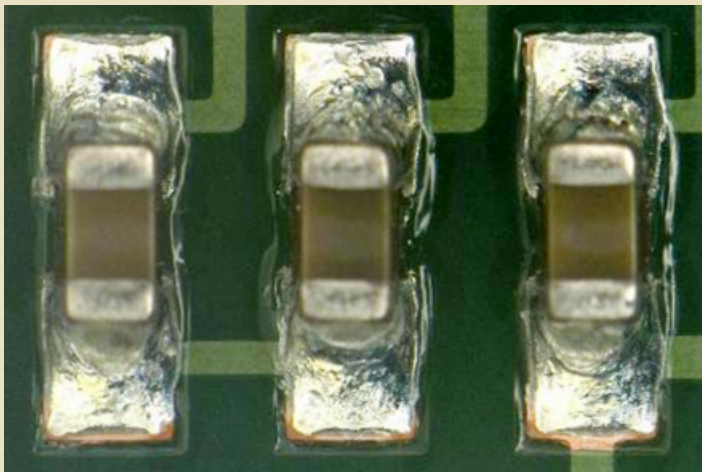
- Long Stencil Life: Engineered for consistent performance in warm and humid climates.
- High Tack Force Life: ensures high pick-and-place yields and good self-alignment.
- Air reflow capable.
- Excellent Head-in-Pillow.



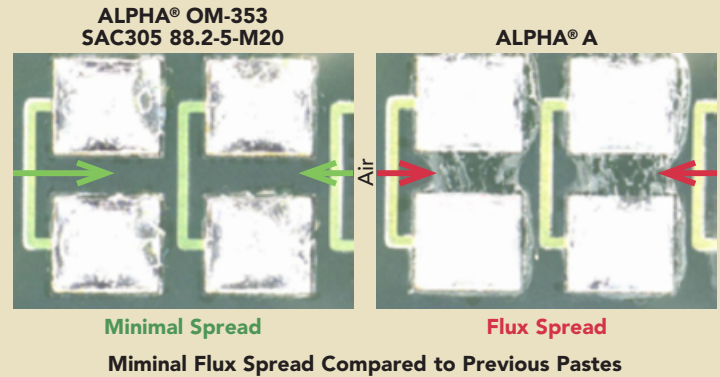
* Zero Halogen is defined as no halogen intentionally added to the formulation.

ALPHA® OM-353 LEAD-FREE, ZERO HALOGEN,* ULTRA FINE-FEATURE SOLDER PASTE

ALPHA® OM-353 solder paste is a versatile product suitable for both SAC305 and SACX® Plus 0307 alloys. Additionally, it is available in both T4 and T5 alloys. With its wide process window, ALPHA® OM-353 meets a wide range of demands in assembly processing lines.



Mid Soak Profile: 1005 Chip Wetting



PERFORMANCE SUMMARY

PROCESS BENEFIT	PROPERTY	PERFORMANCE CAPABILITY
Print Process Window	Fine Feature Print Definition	Excellent Transfer Volume and CpK Efficiency at 180µm circle size
	Tack/Stencil Life	Long Tack and Stencil Life
	Print Speed Range	25 – 150mm/sec (1-6"/sec)
Reflow Process Yield	Reflow Environment	Air and Nitrogen
	Resistance to Voids	Meet IPC 7905 Class III Requirements
	Random Solder Balls	Preferable J-STD-004A and JIS Level 2
	Head in Pillow	Excellent
	Residue Profile	Pin Testable
	Coalescence	160µm circle size (with SAC305, T5 powder)
	Flux Residue Cosmetics	Clear
Electrical Reliability	SIR	Pass J-STD-004B
	Electromigration	Pass JIS-Z-3197-1999 8.5.4
	J-STD-004B Classification	ROLO (Halide Free)
Environmental	Halogen Content	Zero halogen (no halogen intentionally added)



* Zero Halogen is defined as no halogen intentionally added to the formulation.

For more information about ALPHA® OM-353 Lead-Free, Zero Halogen Solder Paste, please contact your Alpha Representative.

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